

# 27th LEEE ULSI TEST SYMPOSIUM (VTS 2009)

Santa Cruz, CA, USA 3-6 May 2009





COMPUTER SOCIETY

# 27th IEEE VLSI TEST SYMPOSIUM SYMPOSIUM COMMITTEES

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New Topics Special Sessions

Innovative Practices Track

Registration

Publicity

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  - P. Varma Blue Pearl
  - Y. Zorian Virage Logic
  - M. Lubaszewski UFRGS
  - E.J. Marinissen IMEC
  - E. J McCluskey Stanford U
  - S. Mourad Santa Clara U
  - P. Muhmenthaler Infineon
  - Z. Navabi Northeastern U
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  - H. Wunderlich U Stuttgart

# 27th IEEE VLSI TEST SYMPOSIUM (VTS 2009)

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# 27th IEEE VLSI TEST SYMPOSIUM VTS 2009 May 3rd - May 6th 2009 Santa Cruz, CA, USA Welcome Message

Welcome to VTS 2009, the twenty-seventh in a series of annual symposia that focus on innovation in the field of testing of integrated circuits and systems.

The core of VTS 2009, the three day technical program, responds to the many trends and challenges in the semiconductor design and manufacturing industries with papers covering a diverse and seminal set of topics including, Fault Models, Transistor Aging and Power Supply Noise, Signal Integrity, Robust Design and Fault Tolerance, Radiation Test, Delay Fault Testing, Analog Test and Calibration, BIST, Microprocessor Test, Verification, Test Compaction, Debug, Diagnosis, Yield, Emergent Technology and Security.

In addition to the three-day technical program, VTS 2009 features several special sessions including several panels addressing various hot topics, two new topic speakers, and two student activity sessions. VTS 2009 continue the tradition of featuring the Innovative Practices track. The sessions that make up this track highlight cutting-edge challenges faced by test practitioners, and innovative solutions employed to address them. This year the Workshop on Test of Wireless Circuits and Systems will take place in conjunction with VTS for the second year.

Two tutorials are offered by the TTTC Tutorials & Education Group through the Test Technology Education Program (TTEP). This year the tutorials cover the exciting topics of Statistical Testing and Silicon Debug and Diagnosis. The tutorials provide opportunities for design and test professionals to update their knowledge base in test, and earn official IEEE TTTC accreditation.

The social program at VTS provides an opportunity for informal technical discussions among participants. Santa Cruz, with its beaches and mountains, provides a very attractive backdrop for all VTS 2009 activities.

# 27th IEEE VLSI TEST SYMPOSIUM VTS 2009 May 3rd - May 6th 2009 Santa Cruz, CA, USA Welcome Message

VTS is the result of the work of many dedicated volunteers: the reviewers, the best paper award judges, the Program Committee, the Organizing Committee, and the Steering Committee. We wholeheartedly thank them all. We also wish to thank all the authors who submitted their works to VTS 2009, and the program participants for their contribution at the symposium. We thank the IEEE Computer Society Test Technology Technical Council for its continued sponsorship and support. Finally, we thank the Corporate Supporters of VTS 2009.

We hope that you will find VTS 2009 enlightening, thoughtprovoking, rewarding, and enjoyable. We wish you all a funfilled and productive week in the Santa Cruz area and hope that you will keep making VTS a success by actively participating in it, assisting in its organization, and letting us always know when we can do something better. Thank you all for coming.

General Chair Magdy Abadir Program Chair Cecilia Metra

# 27th IEEE VLSI TEST SYMPOSIUM Official Sponsors

# The IEEE VLSI TEST SYMPOSIUM is sponsored by the IEEE COMPUTER SOCIETY'S Test Technology Technical Council (TTTC)

The Test Technology Technical Council is a volunteer professional organization sponsored by IEEE Computer Society. Its mission is to contribute to members' professional



development and advancement and to help them solve engineering problems in electronic test, and help advance the state-of-the-art in test technology. TTTC is a prime source of knowledge about electronic test via its conferences, workshops, standards, tutorials and education programs, web site, newsletters, and electronic broadcasts. All its activities are led by volunteer members. TTTC membership is open to all individuals directly or indirectly involved in test technology at a professional level.You may enroll as TTTC member for 2009 (no dues or fees) by using the embedded VTS 2009 Registration Form. To learn more about TTTC offerings and membership benefits, please visit:

#### http://tab.computer.org/tttc





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# 27th IEEE VLSI TEST SYMPOSIUM GENERAL INFORMATION REGISTRATION

The IEEE VLSI Test Symposium explores emerging trends and novel concepts in the testing of integrated circuits and systems. The symposium is a leading international forum where many of the world's leading test experts and professionals from both industry and academia join to present and debate key issues in testing. VTS 2009 addresses key trends and challenges in the semiconductor design and manufacturing industries through an exciting program that includes Keynote and Plenary Talks, Technical Paper Sessions, Embedded Tutorial, Panels, Hot Topic Sessions, Full-day Tutorials, co-located Workshop, and the Innovative Practices Track.

VTS 2009 May 4th to 6th	Advance Rate (Until April 24, 2009)	On-site Rate (After April 24, 2009)
<b>IEEE/CS Member Registration</b> (Member rates are available only to current members of IEEE/CS. Please enter your valid membership number in order to qualify!)	\$525.00	\$630.00
Non-Member Registration	\$660.00	\$800.00
Student, Lifetime/Retired Registration (Valid student ID may be required at onsite registration check-in.)	\$225.00	\$275.00
Student Non-Member Registration	\$325.00	\$375.00
Additional Social Ticket (One Social Ticket is included for those paying IEEE/CS Member or Non-Member VTS rates. Students and companions of registered attendees must purchase a ticket to participate in the social event)	\$100.00	\$100.00

# Symposium Registration

# 27th IEEE VLSI TEST SYMPOSIUM GENERAL INFORMATION REGISTRATION

# **Workshop Registration**

WTW 2009 May 3rd	Advance Rate (Until April 24, 2009)	On-site Rate (After April 24, 2009)
<b>IEEE/CS Member Registration</b> (Member rates are available only to current members of IEEE/CS. Please enter your valid membership number in order to qualify!)	\$220.00	\$275.00
Non-Member Registration	\$275.00	\$345.00
Student, Lifetime/Retired Registration (Valid student ID may be required at onsite registration check-in.)	\$115.00	\$175.00
Half Day Member Registration	\$150.00	\$225.00
Half Day Non-Member Registration	\$190.00	\$290.00

# **TTEP Tutorials Registration**

Tutorial No. 1 - May 3rd Tutorial No. 2 - May 3rd	Advance Rate (Until April 24, 2009)	On-site Rate (After April 24, 2009)
<b>IEEE/CS Member Registration</b> (Member rates are available only to current members of IEEE/CS. Please enter your valid membership number in order to qualify!)	\$320.00	\$385.00
Non-Member Registration	\$400.00	\$480.00

# 27th IEEE VLSI TEST SYMPOSIUM GENERAL INFORMATION LOCATION/ TRAVEL INFO

#### Location:

The City of Santa Cruz, California, is situated on the northern part of Monterey Bay about 74 miles south of San Francisco and 30 miles from San Jose. Santa Cruz is the county seat for the County of Santa Cruz.The City has of an area of 12 square miles.

For more information log on to : http://www.ci.santa-cruz.ca.us/



About Seascape Beach Resort

Located just south of Santa Cruz, Seascape Beach Resort offers 285 luxurious suites and villas overlooking the Monterey Bay. You'll find all the comforts of home, plus the services and amenities of a four-diamond resort. Do anything you like or do nothing at all. With 17 miles of private beach, fine dining, and a full range of activities to choose from, Seascape Beach Resort has everything you need to make your experience memorable.

The resort is 30 miles away from San Jose Airport.

#### To contact the hotel:

Seascape Resort One Seascape Resort Dr. Aptos, CA 95003 831-662-7126 (Phone) 831-685-3059 (FAX)

# 27th IEEE VLSI TEST SYMPOSIUM GENERAL INFORMATION - HOTEL

The reservation cut-off date shall be 4th April 2009 at 5:00 p.m. Pacific time. Reservations received after this date will be accepted by the Hotel on a space available basis at the conference rates. Modifications made to existing reservations after this date will be treated as advance reservations.

# Group rate

Deluxe Suite	\$ 193.00
One Bedroom Beach Villa	\$ 208.00
Two Bedroom Beach Villa	\$ 347.00

The Group Rate covers all guest sleeping room costs, including service fees, and applicable sales/room tax (10%). All the following amenities are also included:

- High-speed internet access in beach villas, studios, suites and select public areas.
- · Use of Fitness Center and Swimming Pool at Seascape Sports Club.
- · All housekeeping and bell staff gratuities.
- · Transportation throughout the resort.

#### 09:00AM - 11:00AM Seascape Grand PLEN Ballroom

#### PLENARY SESSION

Welcome Message: Magdy Abadir, General Chair

Program Introduction: Cecilia Metra, Program Chair

Keynote Speaker: J. Kibarian, CEO and President of PDF Solutions

#### Invited Keynote:

Testing New Generation of Multifunctional Embedded Microsystems B. Kaminska - Canadian Research Chair, Simon Fraser U

#### Awards presentation:

IEEE Fellow Awards TTTC Most Successful Technical Meeting Award TTTC Most Populous Technical Meeting Award VTS 2008 Best Paper Award VTS 2008 Best Panel Award VTS 2008 Best Innovative Practices Award

#### 11:00AM - 11:30AM BREAK

#### 11:30AM - 12:30PM Del Mar

	Moderator: F. Lombardi - Northeastern U
1A.1	<i>Efficient Array Characterization in the UltraSPARC T2</i> T. Ziaja, P. Tan - Sun MicroSystems Inc.
1A.2	Instruction-Level Impact Comparison of RT- vs. Gate-Level Faults in a Modern Microprocessor Controller
	M. Maniatakos, Y. Makris - Yale U, N. Karimi - U of Tehran, C. Tirumurti, A. Jas - Intel
1A.3	Modeling and Testing Comparison Faults of TCAMs with Asymmetric Cells J. F. Li, Y. J. Huang, Y. J. Hu - National Central U

# 11:30AM - 12:30PM

Pacific	Session 1B: <b>FAULT MODELS</b> Moderator: H. J. Wunderlich - Stuttgart U
1B.1	An Electrical Model for the Fault Simulation of Small-Delay Faults Caused by Crosstalk Aggravated Resistive Short Defects N. Houarche, M. Renovell - LIRMM, A. Czutro, P. Engelke, I. Polian, B. Becker - U Freiburg, M. Comte - U of Montpellier
1B.2	Small Delay Fault Model for Intra-Gate Resistive Open Defects M. Arai, A. Suto, K. Iwasaki - Tokyo Metropolitan U, K. Nakano, M. Shintani, K. Hatayama, T. Aikyo - STARC
1B.3	Defect Detection Differences between Launch-Off- Shift and Launch-Off-Capture in Sense-Amplifier- Based Flip Flop Testing

H. Konuk - Broadcom

#### 11:30AM - 12:30PM

# Riviera

#### IP Session 1C: DESIGN AND TEST PRACTICES AND TRENDS IN EAST ASIA Organizer: C. W. Wu - National Tsinghua U Moderator: W. H. Wang - Intel

- 1C.1 Design and Test Practices and Trends, from the Perspective of FTC H. P. Lin - Faraday
- 1C.2 Design and Test Practices and Trends, from the Perspective of GUC J. Lai - Global Unichip
- Design and Test Practices and Trends, from the 1C.3 Perspective of Richtek K. C. Chang - Richtek Technology

#### 12:30PM - 02:15PM LUNCH\*

\*TTTC Service Awards presentation ceremony will take place at lunch venue between 01:00PM -02:15PM

#### 02:15PM - 03:15PM Del Mar

Session 2	A: ROBUST	DESIGN A	ND FAULT
TOLERAN	CE		

Moderator: P. Prinetto - Polit di Torino

- 2A.1 Soft-Error Hardening Designs of Nanoscale CMOS Latches
  - S. Lin, Y. B. Kim, F. Lombardi Northeastern U
- 2A.2 Exploiting Unused Spare Columns to Improve Memory ECC

R. Datta, N. Touba - U of Texas at Austin

 2A.3 An Adaptive-Rate Error Correction Scheme for NAND Flash Memory
 T. H. Chen, Y. Y. Hsiao, Y. T. Hsing, C. W. Wu -National Tsinghua U

#### 02:15PM - 03:15PM Pacific

Session 2B: DELAY FAULT TESTING I
Moderator: V. Agrawal - Auburn U

- 2B.1 Compact Delay Test Generation with a Realistic Low Cost Fault Coverage Metric Z. Wang, D. M. H. Walker - Texas A&M U
- 2B.2 Recursive Path Selection For Delay Fault Testing J. Chung, J. Abraham - U of Texas at Austin
- 2B.3 A Synthesis Method to Alleviate Over-testing of Delay Faults Based on RTL Don't Care Path Identification
   Yoshikawa, T. Inoue - Hiroshima City U,
  - S. Ohtake, H. Fujiwara NIST

# 02:15PM - 03:15PM

Riviera	IP Session 2C: <b>ATE VISION 2020: NEW</b> <b>FRONTIERS FOR ATES</b> Organizer / Moderator: A. Koche - Verigy
2C.1	<i>Test Challenges of Device Scaling</i> R. Barth - ITRS
2C.2	<i>The ATE Inside</i> A. Crouch - Asset-Intertech
2C.3	Getting the Inside Story C. Ritchie - Verigy

03:15PM - 03:45PM BREAK

#### 03:45PM - 04:45PM Del Mar

Del Mar	Session 3A: <b>DEBUG</b> Moderator: Z. Navabi - Northeastern U
3A.1	Automated Selection of Signals to Observe for Efficient Silicon Debug J. S. Yang, N. Touba - U of Texas at Austin
3A.2	A New Post-silicon Debug Approach Based on Suspect Window G. Jianliang - ICT, X. Li, Y. Han - Chinese Academy of Sciences
3A.3	Debug of Speed Path Failures Using Functional Tests S. Venkataraman, R. McLaughlin - Intel

#### 03:45PM - 04:45PM

#### Pacific

Session 3B: **DELAY FAULT TESTING II** Moderator: M. Breuer - U of Southern California

- 3B.1 Output Hazard-Free Transition Delay Fault Test Generation
   S. Menon - AMD, A. Singh, V. Agrawal - Auburn U
- 3B.2 Efficient Scheduling of Path Delay Tests for Latch-Based Circuits
   K. Y. Chung - Samsung, S. Gupta - U of Southern California
- 3B.3 Effective and Efficient Test Pattern Generation for Small Delay Defects
   S. Goel, N. D. Prasanna, R. Turakhia - LSI Corp.

#### 03:45PM - 04:45PM

 

 Rivera
 IP Session 3C: INDUSTRIAL APPROACHES FOR QUALITY AND COMPRESSION Organizer: Y. Sato - Kyushu Institute of Tech. Moderator: M. Arai - Tokyo Metropolitan U

 3C.1
 Test Quality Improvement with Synchronized On-Chip Clocking Y. Onozaki, T. Hasegawa, S. Fujita - Toshiba D. Martin, T. Ayres - Synopsys

- 3C.2 Harmonious BIST: A DFT Approach to Higher Test Coverage and Higher Compression Ratio
   M. Sato, T. Hasegawa, K. Tsutsumida, Y. Sato -Hitachi, V. Chickermane, A. Uzzaman,
   P. Zhang - Cadence
- 3C.3 Logic Depth, Test data Volume & Defects Per Million (DPM): A case study of Ultrasparc T2 SoC Multi-core Microprocessors
   P. Mantri, M. Gala - Sun Micro.

#### 08:00PM - 09:30PM

Del Mar

Special Session 4A: PANEL: APPRENTICE – VTS EDITION: SEASON 2

Organizer / Moderator - K. S. Kim - Intel Panelists:

- A. Crouch Asset-Intertech
- A. Gattiker IBM
- S. Ozev Arizona State U
- B. Cory NVidia
- R. Kapur Synopsys

#### 08:00PM - 09:30PM

#### Pacific

#### Special Session 4B: PANEL: DFT AND TEST PROBLEMS FROM THE TRENCHES

Organizer / Moderator - H. Konuk - *Broadcom Corp.* Panelists:

- Z. Conroy Cisco
- B. Corey NVidia
- R. Aitken ARM

#### 08:00PM - 09:30PM

Riviera

Special Session 4C: **STUDENT POSTERS** Organizers: Y. Makris - Yale U, H. Stratigopoulos -TIMA Moderator: H. Stratigopoulos - TIMA

#### 08:30AM-09:30AM Del Mar

Session 5A: DIAGNOSIS	
Moderator: J. Ferguson, U of Californ	nia, Santa Cruz

- 5A.1 Multiple-Fault Silicon Diagnosis Using Faulty-Region Identification
   M. J. Tasi, C. T. Chao, J. Y. Jou, M. C. Wu -National Chiao Tung U
- 5A.2 Predictive Test Technique for Diagnosis of RF CMOS Receivers
  K. Suenaga, R. Picos, S. Bota, E. Isern, E.G. Moreno, M. Roca -U of Balearic Islands
- 5A.3 Controlling DPPM through Volume Diagnosis X. Yu, Y. T. Lin, R. S. Blanton - Carnegie Mellon U

#### 08:30AM - 09:30AM Pacific

Session 5B: DELAY FAULT TESTING AND SIGNAL INTEGRITY

Moderator: X. Li - Chinese Academy of Sciences

- 5B.1 Scalable Compact Test Pattern Generation for Path Delay Faults Based on Functions
  E. Flanigan, S. Tragoudas, A. A. Rahman -Southern Illinois U
- 5B.2 A Novel Test Application Scheme for High Transition Fault Coverage and Low Test Cost Z. Chen, D. Xiang, B. Yin - Tsinghua U
- 5B.3 A High-Level Signal Integrity Fault Model and Test Methodology for Long On-Chip Interconnections S. Chun, Y. Kim, T. Kim, S. Kang - Yonsei U

# 08:30AM - 09:30AM

Riviera	IP Session 5C: <b>YIELD AND MARGINALITIES</b> Organizer / Moderator: R. Aitken - ARM
5C.1	Trading Off Margin vs. Yield: Is What We Model What We Get? A. Gattiker - IBM
5C.2	Process Variability-Induced Timing Failures C. E. Lew - Qualcomm
5C.3	Can You Blame System Fails On Low Margin? Z. Conroy - Cisco

#### 09:30AM - 10:00AM BREAK

#### 10:00AM - 11:00AM

Del Mar	Session 6A: <b>Yield</b> Moderator: S. Bernard - LIRMM
6A.1	False Path Aware Timing Yield Estimation Under Variability L. Xie, A. Davoodi, K. Saluja, A. Sinkar - U of Wisconsin Madison
6A.2	<ul><li>Bridging DFM Analysis and Volume Diagnostics for Yield Learning</li><li>M. Ward, S. Goel, R Turakhia - LSI Corp.</li><li>B. Benware - Mentor Graphics</li></ul>
6A.3	Yield and Cost Analysis of a Reliable NoC S. Shamshiri, K. T. Cheng - UCSB
10:00AM - 11	00AM

# Pacific

acific	Moderator: S. Hellebrand - U of Paderborn
6B.1	Restrict Encoding for Mixed-Mode BIST
	A. W. Hakmi, S. Holst, H. J. Wunderlich -

- U of Stuttgart, J. Schlöffel, F. Hapke, A.Glowatz -Mentor Graphics
- 6B.2 A Scalable, Digital BIST Circuit for Measurement and Compensation of Static Phase Offset K. Jenkins, L. Li - IBM TJ Watson Research Center
- 6B.3 Experimental Validation of a BIST Technique for CMOS Active Pixel Sensors L. Lizarraga, S. Mir, G. Sicard - TIMA

#### 10:00AM - 11:00AM

Riviera	IP Session 6C: <b>NEW PRACTICES IN</b> <b>DEFECT-BASED TESTING</b> Organizer / Moderator: P. Maxwell - Aptina
6C.1	Test for Reliability of Embedded SRAM P.K. Ahuja - Sun Microsystems
6C.2	Marginal Defects: Are Power-Only Defects Really Defects? J. Fitzgerald - AMD
6C.3	<i>T.B.D.</i> H. Manhaeve - QStar

#### 11:00AM - 11:30AM BREAK

#### 11:30AM-12:30PM

Del Mar	Session 7A: <b>TEST AND VERIFICATION</b> Moderator: S. Davidson - Sun Micro.
7A.1	<i>Physically-Aware N-Detect Test Relaxation</i> Y. T. Lin, C. Ezekwe, R.S. Blanton - Carnegie Mellon U
7A.2	Automatic Selection of Internal Observation Signals for Design Verification T. Lu - Institute of Computing Technology, H. Li, X. Li - Chinese Academy of Sciences
7A.3	S <i>TDF Memory Fail Datalog Standard</i> A. Khoche - Verigy

#### 11:30AM-12:30PM

#### Pacific

#### Session 7B: **TRANSISTOR AGING AND POWER SUPPLY NOISE** Moderator: H. Manhaeve - Qstar

- 7B.1 Test Patterns for Transistor Aging A. H. Baba, S. Mitra - Stanford U
- 7B.2 Layout-Aware Pattern Generation for Maximizing Supply Noise Effects on Critical Paths J. Ma, J. Lee, M.Tehranipoor - U of Connecticut
- 7B.3 Understanding Power Supply Droop During At-Speed Scan Testing P. Pant, J. Zelman - Intel

#### 11:30AM-12:30PM

Riviera	IP Session 7C: VALUE OF DFM IN VOLUME DIAGNOSIS ARENA
	Organizers: S. K. Goel, M. Ward - LSI Corp. Moderator: G. Eide - Mentor Graphics
7C.1	Automation in Silicon Characterization R. Aitken - ARM
7C.2	Using Volume Diagnostics and DFM Practices to Drive Yield Improvement M. Ward - LSI
7C.3	<i>Tying DFM to Test and Volume Diagnosis</i> S. Venkataraman - Intel

#### 12:30PM - 01:30PM LUNCH

#### 01:30PM - 03:00PM

Riviera Special Session 8A: NEW TOPIC: AT-SPEED TESTING IN THE FACE OF PROCESS VARIATIONS Organizer: B. Courtois - TIMA Moderator: X. Gu - Cisco Presenter: C. Visweswariah - IBM

#### 01:30PM - 03:00PM

Pacific Special Session 8B: TTTC 2009 BEST DOCTORAL THESIS CONTEST

> Organizers: Y. Makris - Yale U H. Stratigopoulos - TIMA. Moderator: H. Stratigopoulos - TIMA.

#### 01:30PM - 03:00PM

Del Mar Special Session 8C: Apprentice Panel Judging Session Moderator: K. S. Kim - Intel

#### 03:30PM - 10:00PM

SOCIAL PROGRAM

#### 08:30AM - 09:30AM

Riviera Special Session 9A: NEW TOPIC: MICROSCALE AND NANOSCALE THERMAL CHARACTERIZATION OF INTEGRATED CIRCUIT CHIPS Organizer: B. Courtois - TIMA Moderator: X. Gu - CISCO Presenter: A. Shakouri - U of California, Santa Cruz

#### 08:30AM - 09:30AM

Pacific Special Session 9B: EMBEDDED TUTORIAL: QUANTUM WIRES, QUANTUM WIRE ARRAYS: WHAT ARE THEY ? WHY IS ANYONE INTERESTED? AND HOW DO YOU KNOW YOU HAVE ONE? Moderator: J. Abraham - U of Texas at Austin Presenter: A. Sacco - Northeastern U

#### 09:00AM - 10:00AM BREAK

#### 10:00AM - 11:00AM

#### Del Mar Session 10A: TEST COMPACTION Moderator: C. J. Clark - Intellitech Corp.

- 10A.1 Highly X-Tolerant Selective Compaction of Test Responses
  J. Tyszer, D. Czysz - Poznan U, G. Mrugalski, N. Mukherjee, J. Rajski - Mentor Graphics
- 10A.2 Dynamic Test Compaction for Transition Faults in Broadside Scan Testing Based on an Influence Cone Measure D. Xiang, B. Yin - Tsinghua U, K.-T. Cheng, Z. Chen -UCSB
- 10A.3 Maintaining Accuracy of Test Compaction through Adaptive Modeling S. Biswas, R. S. Blanton - Carnegie Mellon U

#### 10:00AM - 11:00AM

Pacific Session 10B: TEST AND RADIATION TEST Moderator: P. Varma - Blue Pearl

- 10B.1 *RT-Level Deviation-Based Grading of Functional Test Sequences*H. Fang, K. Chakrabarty - Duke U, A. Jas, S. Patil, C.Tirumurti - Intel
- 10B.2 Analytical Model for Multi-site Efficiency with Clustering, Yield and Parallel to Serial Test Times R. Daasch, N Velamati - Portland State U
- 10B.3 DFT Reuse for Low-Cost Radiation Testing of SoCs: a case study
  P. Bernardi, M. Grosso, M. Sonza Reorda - Polit Di Torino, P. Rech, S Gerardin, A.Paccagnella - U di Padova, D. Appello - ST Microelectronics

#### 10:00AM - 11:00AM

RivieraIP Session 10C: DFT AND TEST PRACTICES FOR<br/>POWER-MANAGED LOW POWER CHIPSOrganizers/Moderators: S. Ravi - Texas Instruments,<br/>K. Hatayama - STARC10C.1Manufacturing Test and Silicon Debug Practices for<br/>Power Managed Chips<br/>S. Ravi , A. Bhat - Texas Instruments10C.2An EDA Perspective on Power Management Test<br/>V. Chickermane - Cadence10C.3The Application of CooLBIST for a Real Chip<br/>H. Iwata, J. Matsushima, Y. Maeda, M. Takakura -<br/>Renesas

11:00AM - 11:30AM BREAK

# 11:30PM - 01:00PM

De	el N	lar

#### Session 11A: **ANALOG TEST AND CALIBRATION** Moderator: A. Ivanov - U of British Columbia

- 11A.1 On-line Calibration and Power Optimization of RF Systems Using a Built-in Detector C. Zhang, R. Gharpurey, J. Abraham -U of Texas at Austin
- 11A.2 Calibration and Testing Time Reduction Techniques for a Digitally-Calibrated Pipelined ADC H. M. Chang, C. H. Chen, K. T. Cheng - UCSB K. Y. Lin - Industrial Technology Research Institute
- 11A.3 A Time Domain Method to Measure Oscillator Phase Noise

K. Blakkan - Cypress Semiconductor, M. Soma - U of Washington

11A.4 A Packet Based 2-Site Test Solution for GSM Transceivers with Limited Tester Resources E. Erdogan - Duke U, S. Ozev - Arizona State U

#### 11:30PM - 01:00PM

Pacific

# Session 11B: EMERGENT TECHNOLOGY AND SECURITY

Moderator: J. Tyszer - Poznan U

- 11B.1 Design-for-Testability for Digital Microfluidic Biochips T. Xu, K. Chakrabarty - Duke U
- 11B.2 Stuck-Open Fault Leakage and Testing in Nanometer Technologies
  V. H. Champac, J. Vazquez Hernandez - INAOE,
  C. Hawkins - U New Mexico, J. Segura - U des Illes Ballears
- 11B.3 SS-KTC: A High-Testability Low-Overhead Scan Architecture with Multi-Level Security Integration D. Zhao, U. Chandran - U of Louisiana
- 11B.4 Characterization of Effective Laser Spots during Attacks in the Configuration of a Virtex-II FPGA G. Canivet, R. Leveugle - TIMA, J. Clédières -CEA/LETI, F. Valette - DGA/CELAR, M. Renaudin -TIEMPO

01:00PM - 02:00PM LUNCH

#### 02:00PM - 03:30PM Riviera

#### Special Session 12A: **PANEL: ANALOG TEST AND CHARACTERIZATION: THE LONG ROAD TO REALIZATION**

Organizer: A. Sinha - AMD Moderator: V.Ganti - AMD Panelists: G. Roberts - McGill U

- J. Macri AMD
- M. D'Abreau Sandisk
- S. Sunter Logic Vision

#### 02:00PM - 03:30PM

Pacific

Special Session 12B: PANEL: SOC POWER MANAGEMENT IMPLICATIONS ON VALIDATION AND TESTING

Organizer: B. Kapoor - MIMASIC Moderator: S. Tabatabaei - SiTime Panelists:

B. Kapoor - MIMASIC

S. Hemmady - Synopsys

S.Verma - Conexant

# 27th IEEE VLSI TEST SYMPOSIUM SOCIAL PROGRAM

For this year's social event, we will start at 3:30 PM by taking a bus ride to explore the beautiful California scenery. A trip in California is not complete without a stop at one of its legendary wineries. This year we will visit the Fortino Winery close to the city of Gilroy. You will get to network and socialize while enjoying wine-tasting and a tour of the winery. Buses will return back to the resort to arrive around 7PM.

Once we are back at the resort, we will head to the beach! Dinner will be served on the beautiful beach of the Seascape resort. Dinner festivities will start at 7PM and lasts until 10PM. You will get to enjoy great food and drinks at the beachside accompanied by beautiful California sunset. A fire will be setup as it gets dark into the night. You can continue to enjoy the sounds of the ocean alongside the fire or take a walk on the beach after dinner. Just remember to dress warm as the sea breeze can be a bit cold.

There is no extra cost for this program for VTS attendees who register at member and non-member rates. Students and companions of VTS attendees can register for the Social Program for \$100 per person. So, come and join us!

Useful information: Fortino Winery 4525 Hecker Pass Hwy Gilroy, CA 95020

# 27th IEEE VLSI TEST SYMPOSIUM TEST TECHNOLOGY EDUCATIONAL PROGRAM 2009



The Tutorials and Education Group of TTTC continues the organization of a comprehensive set of test technology tutorials. These comprise tutorials in conjunction with TTTC sponsored technical meetings, web-based tutorials, and on-site tutorials and courses. The tutorials are part of the successful annual Test Technology Educational Program (TTEP 2009).

TTEP intends to serve both test and design professionals by offering

fundamental education and expert knowledge in state-of-the-art test technology topics and also the opportunity to earn official certification from IEEE TTTC. Each six-hour tutorial corresponds to four TTEP units. Upon completion of each sixteen TTEP units official accreditation in the form of an "IEEE TTTC Test Technology Certificate" is presented to the participants.

For further information

Dimitris Gizopoulos Tutorials and Education Group Chair University of Piraeus, Greece Tel: +30 210 414 2372 Email: dgizop@unipi.gr TTEP web site: http://tab.computer.org/tttc/teg/ttep

# 27th IEEE VLSI TEST SYMPOSIUM TUTORIAL 1 Sunday, May 3rd 2009

#### 8:30AM -4:30PM

**Tutorial:** Advanced Topics and Recent Advances in Silicon Debug and Diagnosis

PRESENTERS: S. Venkataraman (Intel), M.Abramovici, R. Aitken (ARM)

**AUDIENCE:** IC Designers; test, DFT, and product engineers; DA developers; validation, debug, and failure analysis engineers; researchers, managers, and anyone else determined to shorten the time-to-volume of a newly manufactured chip

**DESCRIPTION:** The increasing design complexity along with the emergence of new failure mechanisms in the nanometer regime has significantly increased the complexity of verification, validation and manufacturing ramp of ICs. When pre-silicon verification and validation uncovers design bugs, the process of diagnosing and debugging these issues is called design error diagnosis. From the time a new chip comes back from the fab until high-volume production can start, the chip goes through functional silicon validation and debug to make sure it is free of design errors, and defect diagnosis and failure analysis to solve vield problems. These activities, referred to as silicon debug and diagnosis, have become the most time-consuming phase in the development cycle of a new design, increasing to about one third of the total time. This is a consequence of the increasing design complexity, along with the emergence of new failure mechanisms in nanometer technologies. Long time-tovolume and low manufacturing yield have a great detrimental impact on the economic viability and the overall success of a product. This tutorial covers the state of the art and the full spectrum of topics in silicon validation and debug and defect diagnosis ranging from the basic concepts to advanced applications and new DFD techniques. It also describes successful debug and diagnosis methods used in real industrial products, industrial experiences, and case studies, as well as future directions and challenges.

# 27th IEEE VLSI TEST SYMPOSIUM TUTORIAL 2 Sunday, May 3rd 2009

#### 8:30AM -4:30PM

Tutorial: Statistical Adaptive Test Methods Targeting "Zero Defect" IC Quality and Reliability

PRESENTERS: : A. Singh (Auburn University)

**AUDIENCE:** Test and Reliability Engineers, Engineering Managers, Reliability and Quality Assurance Managers, Researchers and Research Students

**DESCRIPTION:** Integrated circuits have traditionally all been tested identically in the manufacturing flow. However, as the detection of subtle manufacturing flaws becomes ever more challenging and expensive in aggressively scaled nanometer technologies, innovative new statistical screening methods are being developed that attempt to improve test effectiveness and optimize test costs by adaptively subjecting "suspect" parts to more extensive testing. The idea is similar to security screening at airports. Such methods fall into two broad categories: those that exploit the statistics of defect distribution on wafers, and those that exploit the correlation in the variation of process and performance parameters on wafers. This tutorial presents test methodologies that span both these categories, and illustrates their effectiveness with results from a number of recently published experimental studies on production circuits from several companies.

# IEEE Workshop on Test of Wireless Circuits and Systems WTW 2009

SCOPE: The Wireless Test Workshop (WTW) includes, among others, the following major topics in RF test: Case Studies, High-Frequency Test, Embedded RF Circuit Test, RF Test Board Related Issues, Yield Learning, Wireless Test Methodology, Standards Conformance Test, Noise Characterization and Validation, Economics of Test, Wireless Product Test Equipment and Metrology.

For this year, the program committee has put together an exciting and a highly technical program, this year main focus is on:

- Challenges and Opportunities in Next Generation RF Transceivers by an Intel Fellow
- 60GHz and beyond test challenges by CEO of Roos Instruments
- 4G test challenges
- Protocol aware HTOL
- System level vs. Parametric test what Strategies Provide the Lowest COT, Highest Quality, Best Yield, & Shortest Time to Volume

The workshop encourages discussion and the technical program is oriented to create an atmosphere that facilitates audience learning and contribution to the subject matter.

#### Advance Program Summary:

- 1 Keynote Speaker: Challenges and Opportunities in Next Generation RF Transceivers
- 2 Invited Speaker: mmWave ATE RFIC Production Test
- 3 Session #2: Min-Tutorial: LTE Test Challenges
- 4 Session #3: Panel: Modulation vs CW Test: What Strategies Provide the Lowest COT, Highest Quality, Best Yield, & Shortest Time to Volume?
- 5 Session #4: Advanced Test Techniques

**REGISTRATION:** All WTW 2009 participants require registration, which includes workshop technical sessions, workshop informal proceedings, break refreshments, and lunch.

**SPONSORSHIP:** WTW 2009 is sponsored by the IEEE Computer Society TTTC.

**INFORMATION:** For further details on the technical program, please contact Program Chair, Mustapha Slamani (slamanim@us.ibm.com). Regarding other questions, please contact the General Chair, Rob Aitken (rob.aitken@arm.com).

#### Please visit our web-site: http://www.wtw2009.tec.ufl.edu/

	27TH IEEE VLSI TEST SYN	27TH IEEE VLSI TEST SYMPOSIUM - PROGRAM AT A GLANCE	GLANCE
Sunday, May 3rd 2009	60		
07:30AM - 08:30AM	REGISTRATION		
08:30AM - 04:30PM	TUTORIAL 1 - Advanced Topics and recent Advances in debug and daignosis		TUTORIAL 2 - Statistical Adaptive Test Methods Targeting "Zero Defect" IC Quality and Reliability
Monday, May 4rd 2009	60		
09:00AM - 11:00AM	PLENARY SESSION		
11:30AM - 12:30AM	Session 1A - Microprocessor Test	Session 1B: Fault Models	Session 1C: Design and Test Practices and Trends in East Asia
12:30PM - 02:15PM	LUNCH & TTTC Service Award Presentation	tation	
02:15PM - 03:15PM	Session 2A: Robust Design and Fault Tolerance	Session 2B: Delay Fault Testing I	Session 2C: ATE Vision 2020: New Frontiers For ATEs
03:45PM - 04:45PM	Session 3A: Debug	Session 3B: Delay Fault Testing II	Session 3C: Industrial Approaches for Quality and Compression
08:00PM - 09:30PM	Session 4A: Panel: Apprentice - VTS Edition: Season 2	Session 4B: Panel: DFT and Test Problems from the Trenches	Session 4C: Student Posters
Tuesday, May 5th 2009	60		
08:30AM - 09:30 AM	Session 5A: Diagnosis	Session 5B: Delay Fault Testing and Signal Integrity	Session 5C: Yield and Marginalities

10:00AM - 11:00AM	Session 6A: Yield	Session 6B: BIST	Session 6C: New Pratices in Defect- Based Testing
11:30AM - 12:30PM	Session 7A: Test and Verification	Session 7B: Transistor Aging and Power Supply Noise	Session 7C: Value of DFM in Volume Diagnosis Arena
12:30PM - 01:30PM	LUNCH		
1:30PM - 3:00PM	Session 8A: New Topic - At Speed         Session 8B: TTTC 2009           Testing in the Face of Process Variations         Doctoral Thesis Contest	Session 8B: TTTC 2009 Best Doctoral Thesis Contest	Session 8C: Apprentice Panel Judging Session
03:30PM - 10:00PM	Social Program		
Wednesday, May 6th	2009		
08:30AM - 09:30AM	Session 9A: New Topic: Microscale and Nanoscale Thermal Characterization of Intergrated Circuit Chips	Session 9B: Embedded Tutorial: Quantum Wires, Quantum Wire Arrays: What are they ? Why is anyone interested ? And how do you know you have one ?	
10:00AM - 11:00AM	Session 10A: Test Compaction	Session 10B: Test and Radiation Test	Session 10B: Test and Radiation Test Session 10C: DFT and Test Practices for Power-Managed Low Power Chips
11:30AM - 01:00PM	Session 11A: Analog Test and Calibration	Session 11B: Emergent Technology and Security	
01:00PM - 02:00PM	LUNCH		
02:00PM - 03:30PM	Session 12A: Panel: Analog Test and Characterization : The long Road to Realization	Session 12B: Panel: SOC Power Management Implications on Validation and Testing	
Innovative Practice Sessions	sions Special Sessions		

# 27th IEEE VLSI TEST SYMPOSIUM FRINGE MEETINGS

A number of TTTC professional groups interested in test will hold their meetings at VTS 2009. At press time, the following meetings were scheduled. These meetings are for members. If you'd like to attend, please contact the person listed at the e-mail address given. Please check with VTS09 onsite registration desk for room locations.

MONDAY, May 4th	
*12:30 pm - 2:15 pm	Test Week Workshop Coordination Yervant Zorian (zorian@viragelogic.com)
2:00 pm - 3:00 pm	TTTC Tutorials and Education Group Dimitris Gizopoulos (dgizop@unipi.gr)
3:00 pm - 4:00 pm	TTTC Executive Committee Adit Singh (adsingh@eng.auburn.edu)
4:00 pm - 5:00 pm	ITRS Test Open Meeting Mike Rodgers (mjrodge2@sbcglobal.net)
5:00 pm - 6:00 pm	TTTC Senior Leadership Board Yervant Zorian (zorian@viragelogic.com)
**6:00 pm - 8:00 pm	IEEE VTS Program Committee Cecilia Metra (cecilia.metra@deis.unibo.it)
TUESDAY, May 5th	
8:00 am - 9:30 am	TTTC Technical Meetings Review Committee Chen-Huan Chiang (chenhuan@alcatel- lucent.com)
11:00 am - 12:00 pm	ITRS DFT SubTeam Yervant Zorian (zorian@viragelogic.com)
*12:30 pm - 1:30 pm	TTTC Standards Group Rohit Kapur (rohit.kapur@synopsys.com)
*12:30 pm - 1:30 pm	Int'l OnLine Test Symposium Committee Michael Nicolaidis (michael.nicolaidis@imag.fr)
2:00 pm - 3:00 pm	TTTC Communications Group Cecilia Metra (cecilia.metra@deis.unibo.it)
WEDNESDAY, May 6th	
8:00 am - 9:30 am	TTTC Operations Committee Adit Singh (adsingh@eng.auburn.edu)
11:00 am - 1:00 pm	IEEE VTS Organizing Committee Magdy Abadir (M.Abadir@freescale.com)
*1:00 pm - 2:00 pm	TTTC Middle East and Africa Group Rafic Makki (makki@uaeu.ac.ae)

\*Meeting During Lunch Break \*\*Meeting During Dinner